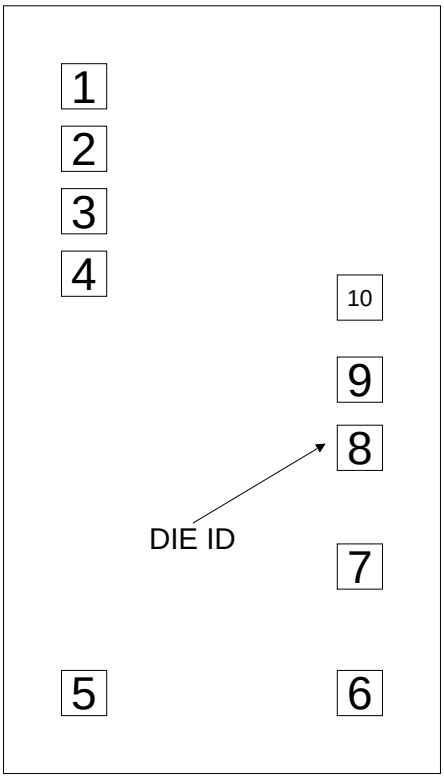
LMV242 MDA
Dual Output, Quad-Band GSM/GPRS Power Amplifier Controller

DEC 15, 2009

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMV242A	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	200mm	Back Side Metal	BAREBACK
Die Size (Drawn)	889.00µm x 1562.10µm 35.0mils x 61.5mils	Back Side Connection	Floating
Thickness	216µm Nominal		
Min Pitch	127.10µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
OUTPUT1	1	-281	617	92	x	92
OUTPUT2	2	-281	490	92	x	92
COMP 2	3	-281	363	92	x	92
VDD	4	-281	236	92	x	92
RFIN	5	-281	-617	92	x	92
VRAMP	6	281	-617	92	x	92
TX EN	7	281	-360	92	x	92
BS	8	281	-118	92	x	92
COMP1	9	281	20	92	x	92
GND	10	281	187	92	x	92

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Notes

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